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- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))
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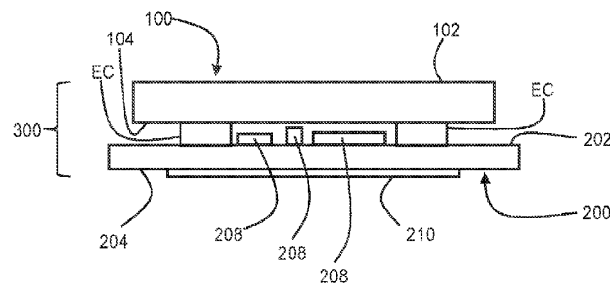
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- (54) **Title:** SYSTEM AND METHOD FOR MANUFACTURING AND ASSEMBLING PACKAGED ELECTRONIC MODULES

FIG. 1



- (57) **Abstract:** A system and method of manufacturing and/or assembling packaged electronic modules for use with smart cards is disclosed. The packaged electronic modules may include contact plate(s), printed circuit(s) and/or value add components such as displays.



WO 2021/206780 A1